



## The Fabrication of Microstructures from Powders and Their Applications in Microsystems

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### Message from the Guest Editor

This Special Issue seeks to showcase research papers and review articles that focus on: (1) powder-based techniques for 3D microstructure fabrication compatible to silicon, glass, ceramic or plastic substrates, panels or boards; (2) simulation and characterization of powder-based 3D microstructures fabricated from various materials; (3) fabrication, simulation and characterization of MEMS devices utilizing powder-based 3D microstructures; (4) novel functionalities and applications for MEMS due to powder-based 3D microstructures; (5) durability, reliability and long-term stability of powder-based 3D microstructures.

- powder-based techniques
- 3D microstructures
- MEMS





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